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## What is "Embedded - Microcontrollers"?

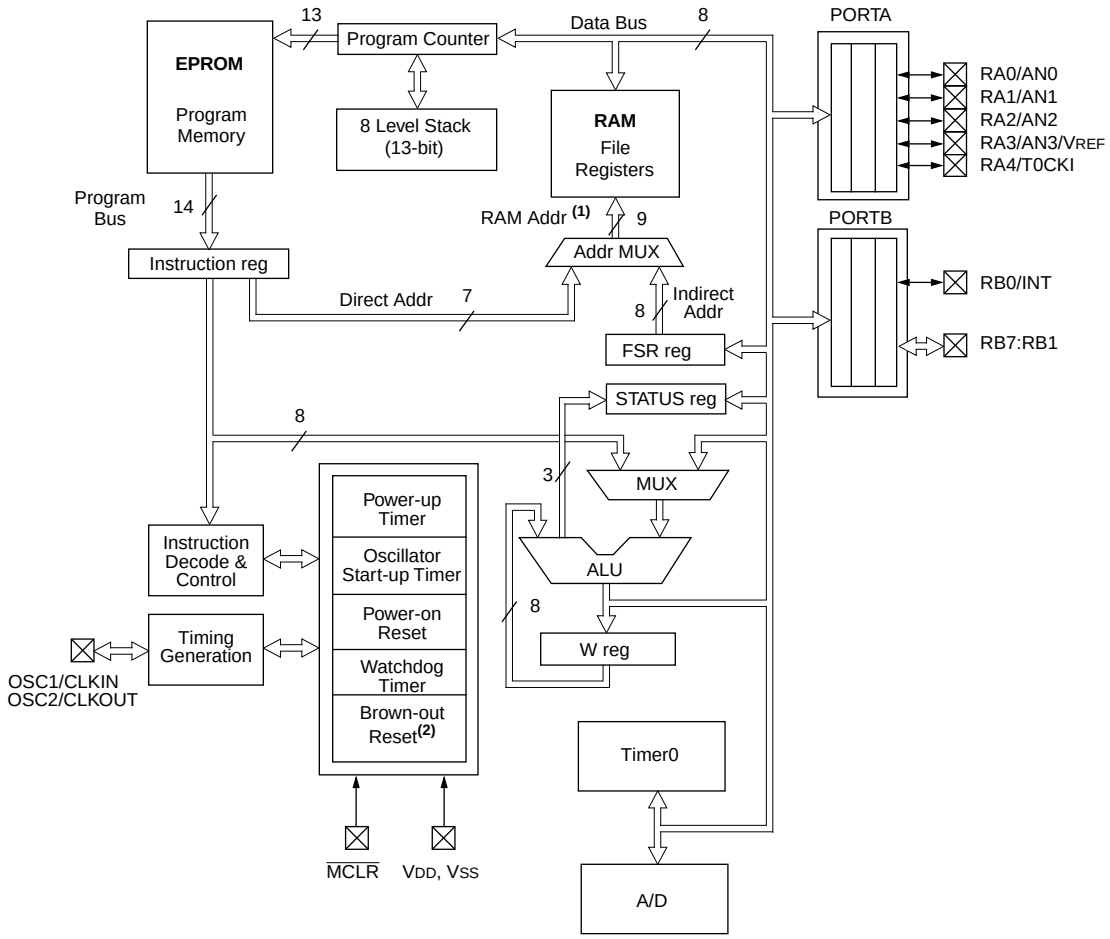
"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

## Applications of "Embedded - Microcontrollers"

| Details | |
|---|---|
| Product Status | Active |
| Core Processor | PIC |
| Core Size | 8-Bit |
| Speed | 4MHz |
| Connectivity | - |
| Peripherals | Brown-out Detect/Reset, POR, WDT |
| Number of I/O | 13 |
| Program Memory Size | 3.5KB (2K x 14) |
| Program Memory Type | OTP |
| EEPROM Size | - |
| RAM Size | 128 x 8 |
| Voltage - Supply (Vcc/Vdd) | 4V ~ 5.5V |
| Data Converters | A/D 4x8b |
| Oscillator Type | External |
| Operating Temperature | 0°C ~ 70°C (TA) |
| Mounting Type | Surface Mount |
| Package / Case | 20-SSOP (0.209", 5.30mm Width) |
| Supplier Device Package | 20-SSOP |
| Purchase URL | https://www.e-xfl.com/product-detail/microchip-technology/pic16c715t-04-ss |

**FIGURE 3-1: PIC16C71X BLOCK DIAGRAM**

| Device | Program Memory | Data Memory (RAM) |
|---|---|---|
| PIC16C710 | 512 x 14 | 36 x 8 |
| PIC16C71 | 1K x 14 | 36 x 8 |
| PIC16C711 | 1K x 14 | 68 x 8 |
| PIC16C715 | 2K x 14 | 128 x 8 |




Note 1: Higher order bits are from the STATUS register.
2: Brown-out Reset is not available on the PIC16C71.


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**TABLE 5-1: PORTA FUNCTIONS**

| Name | Bit# | Buffer | Function |
|---|---|---|---|
| RA0/AN0 | bit0 | TTL | Input/output or analog input |
| RA1/AN1 | bit1 | TTL | Input/output or analog input |
| RA2/AN2 | bit2 | TTL | Input/output or analog input |
| RA3/AN3/VREF | bit3 | TTL | Input/output or analog input/VREF |
| RA4/T0CKI | bit4 | ST | Input/output or external clock input for Timer0<br>Output is open drain type |

Legend: TTL = TTL input, ST = Schmitt Trigger input

**TABLE 5-2: SUMMARY OF REGISTERS ASSOCIATED WITH PORTA**

| Address | Name | Bit 7 | Bit 6 | Bit 5 | Bit 4 | Bit 3 | Bit 2 | Bit 1 | Bit 0 | Value on: POR, BOR | Value on all other resets |
|---|---|---|---|---|---|---|---|---|---|---|---|
| 05h | PORTA | — | — | — | RA4 | RA3 | RA2 | RA1 | RA0 | ---x 0000 | ---u 0000 |
| 85h | TRISA | — | — | — | PORTA Data Direction Register | | | | | ---1 1111 | ---1 1111 |
| 9Fh | ADCON1 | — | — | — | — | — | — | PCFG1 | PCFG0 | ---- --00 | ---- --00 |

Legend: x = unknown, u = unchanged, - = unimplemented locations read as '0'. Shaded cells are not used by PORTA.


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### 7.1 A/D Acquisition Requirements

For the A/D converter to meet its specified accuracy, the charge holding capacitor (CHOLD) must be allowed to fully charge to the input channel voltage level. The analog input model is shown in Figure 7-5. The source impedance (RS) and the internal sampling switch (RSS) impedance directly affect the time required to charge the capacitor CHOLD. The sampling switch (RSS) impedance varies over the device voltage (VDD), Figure 7-5. The source impedance affects the offset voltage at the analog input (due to pin leakage current). **The maximum recommended impedance for analog sources is 10 kΩ.** After the analog input channel is selected (changed) this acquisition must be done before the conversion can be started.

To calculate the minimum acquisition time, Equation 7-1 may be used. This equation calculates the acquisition time to within 1/2 LSb error is used (512 steps for the A/D). The 1/2 LSb error is the maximum error allowed for the A/D to meet its specified accuracy.

**EQUATION 7-1: A/D MINIMUM CHARGING TIME**

$V_{HOLD} = (V_{REF} - (V_{REF}/512)) \cdot (1 - e^{(-T_{CAP}/C_{HOLD}(R_{IC} + R_{SS} + R_S))})$

Given: $V_{HOLD} = (V_{REF}/512)$, for 1/2 LSb resolution

The above equation reduces to:

$T_{CAP} = -(51.2\ pF)(1\ k\Omega + R_{SS} + R_S) \ln(1/511)$

Example 7-1 shows the calculation of the minimum required acquisition time TACQ. This calculation is based on the following system assumptions.

CHOLD = 51.2 pF

Rs = 10 kΩ

1/2 LSb error

VDD = 5V → Rss = 7 kΩ

Temp (application system max.) = 50°C

VHOLD = 0 @ t = 0

**Note 1:** The reference voltage (VREF) has no effect on the equation, since it cancels itself out.

**Note 2:** The charge holding capacitor (CHOLD) is not discharged after each conversion.

**Note 3:** The maximum recommended impedance for analog sources is 10 kΩ. This is required to meet the pin leakage specification.

**Note 4:** After a conversion has completed, a 2.0TAD delay must complete before acquisition can begin again. During this time the holding capacitor is not connected to the selected A/D input channel.

**EXAMPLE 7-1: CALCULATING THE MINIMUM REQUIRED AQUISITION TIME**

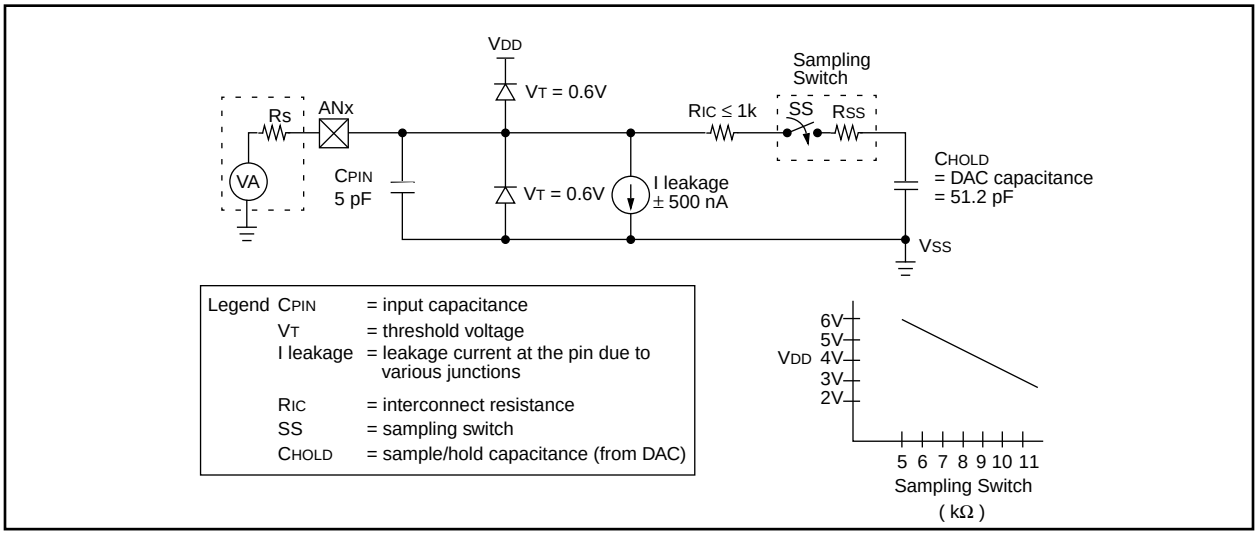
TACQ = Amplifier Settling Time +
Holding Capacitor Charging Time +
Temperature Coefficient

TACQ = 5 µs + TCAP + [(Temp - 25°C)(0.05 µs/°C)]

TCAP = -CHOLD (RIC + RSS + RS) ln(1/511)
-51.2 pF (1 kΩ + 7 kΩ + 10 kΩ) ln(0.0020)
-51.2 pF (18 kΩ) ln(0.0020)
-0.921 µs (-6.2364)
5.747 µs

TACQ = 5 µs + 5.747 µs + [(50°C - 25°C)(0.05 µs/°C)]
10.747 µs + 1.25 µs
11.997 µs

**FIGURE 7-5: ANALOG INPUT MODEL**





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## 8.5 Interrupts

| Applicable Devices | 710 | 71 | 711 | 715 |
|---|---|---|---|---|

The PIC16C71X family has 4 sources of interrupt.

| Interrupt Sources |
|---|
| External interrupt RB0/INT |
| TMR0 overflow interrupt |
| PORTB change interrupts (pins RB7:RB4) |
| A/D Interrupt |

The interrupt control register (INTCON) records individual interrupt requests in flag bits. It also has individual and global interrupt enable bits.

**Note:** Individual interrupt flag bits are set regardless of the status of their corresponding mask bit or the GIE bit.

A global interrupt enable bit, GIE (INTCON<7>) enables (if set) all un-masked interrupts or disables (if cleared) all interrupts. When bit GIE is enabled, and an interrupt's flag bit and mask bit are set, the interrupt will vector immediately. Individual interrupts can be disabled through their corresponding enable bits in various registers. Individual interrupt bits are set regardless of the status of the GIE bit. The GIE bit is cleared on reset.

The "return from interrupt" instruction, RETFIE, exits the interrupt routine as well as sets the GIE bit, which re-enables interrupts.

The RB0/INT pin interrupt, the RB port change interrupt and the TMR0 overflow interrupt flags are contained in the INTCON register.

The peripheral interrupt flags are contained in the special function registers PIR1 and PIR2. The corresponding interrupt enable bits are contained in special function registers PIE1 and PIE2, and the peripheral interrupt enable bit is contained in special function register INTCON.

When an interrupt is responded to, the GIE bit is cleared to disable any further interrupt, the return address is pushed onto the stack and the PC is loaded with 0004h. Once in the interrupt service routine the source(s) of the interrupt can be determined by polling the interrupt flag bits. The interrupt flag bit(s) must be cleared in software before re-enabling interrupts to avoid recursive interrupts.

For external interrupt events, such as the INT pin or PORTB change interrupt, the interrupt latency will be three or four instruction cycles. The exact latency depends when the interrupt event occurs (Figure 8-19). The latency is the same for one or two cycle instructions. Individual interrupt flag bits are set regardless of the status of their corresponding mask bit or the GIE bit.

**Note:** For the PIC16C71
If an interrupt occurs while the Global Interrupt Enable (GIE) bit is being cleared, the GIE bit may unintentionally be re-enabled by the user's Interrupt Service Routine (the RETFIE instruction). The events that would cause this to occur are:

1. An instruction clears the GIE bit while an interrupt is acknowledged.
2. The program branches to the Interrupt vector and executes the Interrupt Service Routine.
3. The Interrupt Service Routine completes with the execution of the RETFIE instruction. This causes the GIE bit to be set (enables interrupts), and the program returns to the instruction after the one which was meant to disable interrupts.

Perform the following to ensure that interrupts are globally disabled:

```
LOOP BCF   INTCON, GIE  ; Disable global
                        ;  interrupt bit
     BTFSC INTCON, GIE  ; Global interrupt
                        ;   disabled?
     GOTO  LOOP         ; NO, try again
        :               ;   Yes, continue
                        ;   with program
                        ;   flow
```

## 8.7 Watchdog Timer (WDT)

| Applicable Devices | 710 | 71 | 711 | 715 |
|---|---|---|---|---|

The Watchdog Timer is as a free running on-chip RC oscillator which does not require any external components. This RC oscillator is separate from the RC oscillator of the OSC1/CLKIN pin. That means that the WDT will run, even if the clock on the OSC1/CLKIN and OSC2/CLKOUT pins of the device has been stopped, for example, by execution of a SLEEP instruction. During normal operation, a WDT time-out generates a device RESET (Watchdog Timer Reset). If the device is in SLEEP mode, a WDT time-out causes the device to wake-up and continue with normal operation (Watchdog Timer Wake-up). The WDT can be permanently disabled by clearing configuration bit WDTE (Section 8.1).

### 8.7.1 WDT PERIOD

The WDT has a nominal time-out period of 18 ms, (with no prescaler). The time-out periods vary with temperature, VDD and process variations from part to part (see DC specs). If longer time-out periods are desired, a prescaler with a division ratio of up to 1:128 can be assigned to the WDT under software control by writing to the OPTION register. Thus, time-out periods up to 2.3 seconds can be realized.

The CLRWDT and SLEEP instructions clear the WDT and the postscaler, if assigned to the WDT, and prevent it from timing out and generating a device RESET condition.

The $\overline{TO}$ bit in the STATUS register will be cleared upon a Watchdog Timer time-out.

### 8.7.2 WDT PROGRAMMING CONSIDERATIONS

It should also be taken into account that under worst case conditions (VDD = Min., Temperature = Max., and max. WDT prescaler) it may take several seconds before a WDT time-out occurs.

| **Note:** | When a CLRWDT instruction is executed and the prescaler is assigned to the WDT, the prescaler count will be cleared, but the prescaler assignment is not changed. |
|---|---|

**FIGURE 8-20: WATCHDOG TIMER BLOCK DIAGRAM**

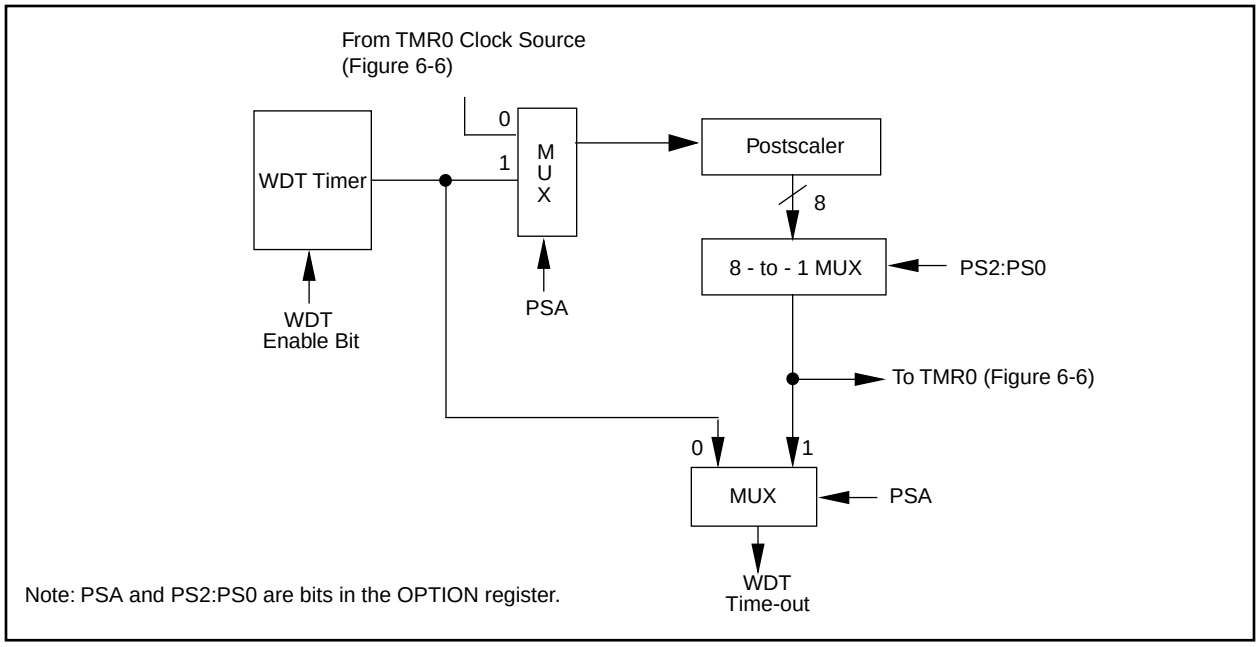


**FIGURE 8-21: SUMMARY OF WATCHDOG TIMER REGISTERS**

| Address | Name | Bit 7 | Bit 6 | Bit 5 | Bit 4 | Bit 3 | Bit 2 | Bit 1 | Bit 0 |
|---|---|---|---|---|---|---|---|---|---|
| 2007h | Config. bits | **(1)** | BODEN(1) | CP1 | CP0 | PWRTE(1) | WDTE | FOSC1 | FOSC0 |
| 81h,181h | OPTION | $\overline{RBPU}$ | INTEDG | T0CS | T0SE | PSA | PS2 | PS1 | PS0 |

Legend: Shaded cells are not used by the Watchdog Timer.
Note 1: See Figure 8-1, Figure 8-2 and Figure 8-3 for operation of these bits.

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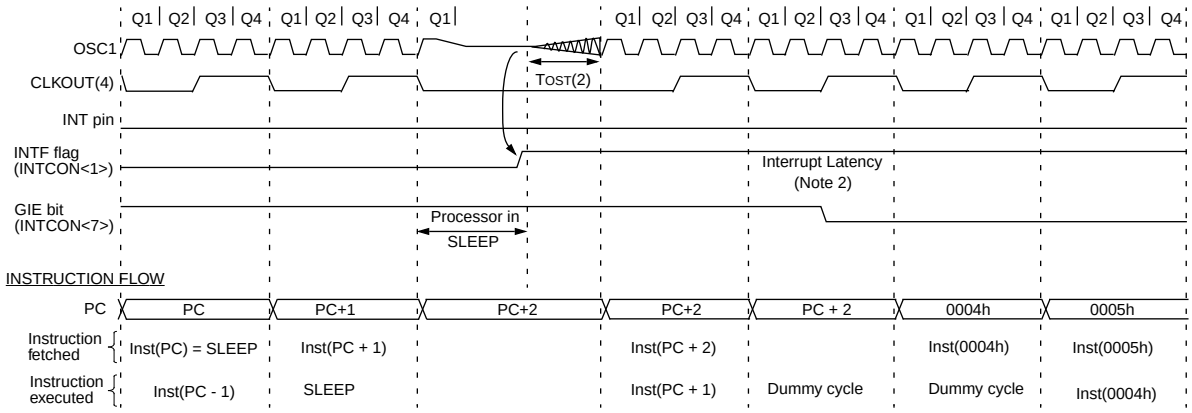
**FIGURE 8-22: WAKE-UP FROM SLEEP THROUGH INTERRUPT**




Note 1: XT, HS or LP oscillator mode assumed.
2: TOST = 1024TOSC (drawing not to scale) This delay will not be there for RC osc mode.
3: GIE = '1' assumed. In this case after wake- up, the processor jumps to the interrupt routine. If GIE = '0', execution will continue in-line.
4: CLKOUT is not available in these osc modes, but shown here for timing reference.

## 8.9 Program Verification/Code Protection

If the code protection bit(s) have not been programmed, the on-chip program memory can be read out for verification purposes.

| **Note:** | Microchip does not recommend code protecting windowed devices. |
|---|---|

## 8.10 ID Locations

Four memory locations (2000h - 2003h) are designated as ID locations where the user can store checksum or other code-identification numbers. These locations are not accessible during normal execution but are readable and writable during program/verify. It is recommended that only the 4 least significant bits of the ID location are used.

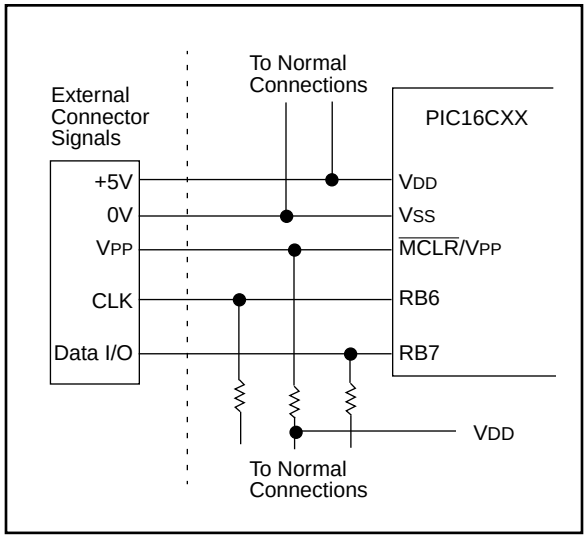
## 8.11 In-Circuit Serial Programming

PIC16CXX microcontrollers can be serially programmed while in the end application circuit. This is simply done with two lines for clock and data, and three other lines for power, ground, and the programming voltage. This allows customers to manufacture boards with unprogrammed devices, and then program the microcontroller just before shipping the product. This also allows the most recent firmware or a custom firmware to be programmed.

The device is placed into a program/verify mode by holding the RB6 and RB7 pins low while raising the $\overline{MCLR}$ ($V_{PP}$) pin from $V_{IL}$ to $V_{IHH}$ (see programming specification). RB6 becomes the programming clock and RB7 becomes the programming data. Both RB6 and RB7 are Schmitt Trigger inputs in this mode.

After reset, to place the device into programming/verify mode, the program counter (PC) is at location 00h. A 6-bit command is then supplied to the device. Depending on the command, 14-bits of program data are then supplied to or from the device, depending if the command was a load or a read. For complete details of serial programming, please refer to the PIC16C6X/7X Programming Specifications (Literature #DS30228).

**FIGURE 8-23: TYPICAL IN-CIRCUIT SERIAL PROGRAMMING CONNECTION**



**BTFSS** **Bit Test f, Skip if Set**

Syntax: [*label*] BTFSS f,b

Operands: 0 ≤ f ≤ 127
0 ≤ b < 7

Operation: skip if (f<b>) = 1

Status Affected: None

Encoding:

| | | | |
|---|---|---|---|
| 01 | 11bb | bfff | ffff |

Description: If bit 'b' in register 'f' is '0' then the next instruction is executed.
If bit 'b' is '1', then the next instruction is discarded and a NOP is executed instead, making this a 2TCY instruction.

Words: 1

Cycles: 1(2)

Q Cycle Activity:

| Q1 | Q2 | Q3 | Q4 |
|---|---|---|---|
| Decode | Read register 'f' | Process data | NOP |

If Skip: (2nd Cycle)

| Q1 | Q2 | Q3 | Q4 |
|---|---|---|---|
| NOP | NOP | NOP | NOP |

Example

```
HERE    BTFSC   FLAG,1
FALSE   GOTO    PROCESS_CODE
TRUE    •
        •
        •
```

Before Instruction
PC = address HERE
After Instruction
if FLAG<1> = 0,
PC = address FALSE
if FLAG<1> = 1,
PC = address TRUE

**CALL** **Call Subroutine**

Syntax: [ *label* ] CALL k

Operands: 0 ≤ k ≤ 2047

Operation: (PC)+ 1→ TOS,
k → PC<10:0>,
(PCLATH<4:3>) → PC<12:11>

Status Affected: None

Encoding:

| | | | |
|---|---|---|---|
| 10 | 0kkk | kkkk | kkkk |

Description: Call Subroutine. First, return address (PC+1) is pushed onto the stack. The eleven bit immediate address is loaded into PC bits <10:0>. The upper bits of the PC are loaded from PCLATH. CALL is a two cycle instruction.

Words: 1

Cycles: 2

Q Cycle Activity:

| | Q1 | Q2 | Q3 | Q4 |
|---|---|---|---|---|
| 1st Cycle | Decode | Read literal 'k', Push PC to Stack | Process data | Write to PC |
| 2nd Cycle | NOP | NOP | NOP | NOP |

Example

```
HERE    CALL    THERE
```

Before Instruction
PC = Address HERE
After Instruction
PC = Address THERE
TOS = Address HERE+1

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**NOP** **No Operation**

Syntax: [ *label* ] NOP

Operands: None

Operation: No operation

Status Affected: None

Encoding:

| | | | |
|---|---|---|---|
| 00 | 0000 | 0xx0 | 0000 |

Description: No operation.

Words: 1

Cycles: 1

Q Cycle Activity:

| Q1 | Q2 | Q3 | Q4 |
|---|---|---|---|
| Decode | NOP | NOP | NOP |

Example

```
NOP
```

**OPTION** **Load Option Register**

Syntax: [ *label* ] OPTION

Operands: None

Operation: (W) → OPTION

Status Affected: None

Encoding:

| | | | |
|---|---|---|---|
| 00 | 0000 | 0110 | 0010 |

Description: The contents of the W register are loaded in the OPTION register. This instruction is supported for code compatibility with PIC16C5X products. Since OPTION is a readable/writable register, the user can directly address it.

Words: 1

Cycles: 1

Example

**To maintain upward compatibility with future PIC16CXX products, do not use this instruction.**

**RETFIE** **Return from Interrupt**

Syntax: [ *label* ] RETFIE

Operands: None

Operation: TOS → PC,
1 → GIE

Status Affected: None

Encoding:

| | | | |
|---|---|---|---|
| 00 | 0000 | 0000 | 1001 |

Description: Return from Interrupt. Stack is POPed and Top of Stack (TOS) is loaded in the PC. Interrupts are enabled by setting Global Interrupt Enable bit, GIE (INTCON<7>). This is a two cycle instruction.

Words: 1

Cycles: 2

Q Cycle Activity:

| | Q1 | Q2 | Q3 | Q4 |
|---|---|---|---|---|
| 1st Cycle | Decode | NOP | Set the GIE bit | Pop from the Stack |
| 2nd Cycle | NOP | NOP | NOP | NOP |

Example

```
RETFIE
```

After Interrupt
PC = TOS
GIE = 1

**SUBWF** **Subtract W from f**

Syntax: [ *label* ] SUBWF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (f) - (W) → (dest)

Status Affected: C, DC, Z

Encoding:

| 00 | 0010 | dfff | ffff |
|---|---|---|---|

Description: Subtract (2's complement method) W register from register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is 1 the result is stored back in register 'f'.

Words: 1

Cycles: 1

Q Cycle Activity:

| Q1 | Q2 | Q3 | Q4 |
|---|---|---|---|
| Decode | Read register 'f' | Process data | Write to dest |

Example 1: SUBWF REG1,1

Before Instruction
REG1 = 3
W = 2
C = ?
Z = ?

After Instruction
REG1 = 1
W = 2
C = 1; result is positive
Z = 0

Example 2: Before Instruction
REG1 = 2
W = 2
C = ?
Z = ?

After Instruction
REG1 = 0
W = 2
C = 1; result is zero
Z = 1

Example 3: Before Instruction
REG1 = 1
W = 2
C = ?
Z = ?

After Instruction
REG1 = 0xFF
W = 2
C = 0; result is negative
Z = 0

**SWAPF** **Swap Nibbles in f**

Syntax: [ *label* ] SWAPF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (f<3:0>) → (dest<7:4>),
(f<7:4>) → (dest<3:0>)

Status Affected: None

Encoding:

| 00 | 1110 | dfff | ffff |
|---|---|---|---|

Description: The upper and lower nibbles of register 'f' are exchanged. If 'd' is 0 the result is placed in W register. If 'd' is 1 the result is placed in register 'f'.

Words: 1

Cycles: 1

Q Cycle Activity:

| Q1 | Q2 | Q3 | Q4 |
|---|---|---|---|
| Decode | Read register 'f' | Process data | Write to dest |

Example
```
SWAPF REG, 0
```
Before Instruction
REG1 = 0xA5

After Instruction
REG1 = 0xA5
W = 0x5A

**TRIS** **Load TRIS Register**

Syntax: [*label*] TRIS f

Operands: $5 \le f \le 7$

Operation: (W) → TRIS register f;

Status Affected: None

Encoding:

| 00 | 0000 | 0110 | 0fff |
|---|---|---|---|

Description: The instruction is supported for code compatibility with the PIC16C5X products. Since TRIS registers are readable and writable, the user can directly address them.

Words: 1

Cycles: 1

Example

**To maintain upward compatibility with future PIC16CXX products, do not use this instruction.**

### 10.6 PICDEM-1 Low-Cost PIC16/17 Demonstration Board

The PICDEM-1 is a simple board which demonstrates the capabilities of several of Microchip's microcontrollers. The microcontrollers supported are: PIC16C5X (PIC16C54 to PIC16C58A), PIC16C61, PIC16C62X, PIC16C71, PIC16C8X, PIC17C42, PIC17C43 and PIC17C44. All necessary hardware and software is included to run basic demo programs. The users can program the sample microcontrollers provided with the PICDEM-1 board, on a PRO MATE II or PICSTART-Plus programmer, and easily test firmware. The user can also connect the PICDEM-1 board to the PICMASTER emulator and download the firmware to the emulator for testing. Additional prototype area is available for the user to build some additional hardware and connect it to the microcontroller socket(s). Some of the features include an RS-232 interface, a potentiometer for simulated analog input, push-button switches and eight LEDs connected to PORTB.

### 10.7 PICDEM-2 Low-Cost PIC16CXX Demonstration Board

The PICDEM-2 is a simple demonstration board that supports the PIC16C62, PIC16C64, PIC16C65, PIC16C73 and PIC16C74 microcontrollers. All the necessary hardware and software is included to run the basic demonstration programs. The user can program the sample microcontrollers provided with the PICDEM-2 board, on a PRO MATE II programmer or PICSTART-Plus, and easily test firmware. The PICMASTER emulator may also be used with the PICDEM-2 board to test firmware. Additional prototype area has been provided to the user for adding additional hardware and connecting it to the microcontroller socket(s). Some of the features include a RS-232 interface, push-button switches, a potentiometer for simulated analog input, a Serial EEPROM to demonstrate usage of the $I^2C$ bus and separate headers for connection to an LCD module and a keypad.

### 10.8 PICDEM-3 Low-Cost PIC16CXXX Demonstration Board

The PICDEM-3 is a simple demonstration board that supports the PIC16C923 and PIC16C924 in the PLCC package. It will also support future 44-pin PLCC microcontrollers with a LCD Module. All the necessary hardware and software is included to run the basic demonstration programs. The user can program the sample microcontrollers provided with the PICDEM-3 board, on a PRO MATE II programmer or PICSTART Plus with an adapter socket, and easily test firmware. The PICMASTER emulator may also be used with the PICDEM-3 board to test firmware. Additional prototype area has been provided to the user for adding hardware and connecting it to the microcontroller socket(s). Some of the features include an RS-232 interface, push-button switches, a potentiometer for simulated analog input, a thermistor and separate headers for connection to an external LCD module and a keypad. Also provided on the PICDEM-3 board is an LCD panel, with 4 commons and 12 segments, that is capable of displaying time, temperature and day of the week. The PICDEM-3 provides an additional RS-232 interface and Windows 3.1 software for showing the demultiplexed LCD signals on a PC. A simple serial interface allows the user to construct a hardware demultiplexer for the LCD signals.

### 10.9 MPLAB Integrated Development Environment Software

The MPLAB IDE Software brings an ease of software development previously unseen in the 8-bit microcontroller market. MPLAB is a windows based application which contains:

- A full featured editor
- Three operating modes
  - editor
  - emulator
  - simulator
- A project manager
- Customizable tool bar and key mapping
- A status bar with project information
- Extensive on-line help

MPLAB allows you to:

- Edit your source files (either assembly or 'C')
- One touch assemble (or compile) and download to PIC16/17 tools (automatically updates all project information)
- Debug using:
  - source files
  - absolute listing file
- Transfer data dynamically via DDE (soon to be replaced by OLE)
- Run up to four emulators on the same PC

The ability to use MPLAB with Microchip's simulator allows a consistent platform and the ability to easily switch from the low cost simulator to the full featured emulator with minimal retraining due to development tools.

### 10.10 Assembler (MPASM)

The MPASM Universal Macro Assembler is a PC-hosted symbolic assembler. It supports all microcontroller series including the PIC12C5XX, PIC14000, PIC16C5X, PIC16CXXX, and PIC17CXX families.

MPASM offers full featured Macro capabilities, conditional assembly, and several source and listing formats. It generates various object code formats to support Microchip's development tools as well as third party programmers.

MPASM allows full symbolic debugging from PICMASTER, Microchip's Universal Emulator System.


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| Applicable Devices | 710 | 71 | 711 | 715 |
|---|---|---|---|---|

**11.3 DC Characteristics: PIC16C710-04 (Commercial, Industrial, Extended)**
**PIC16C711-04 (Commercial, Industrial, Extended)**
**PIC16C710-10 (Commercial, Industrial, Extended)**
**PIC16C711-10 (Commercial, Industrial, Extended)**
**PIC16C710-20 (Commercial, Industrial, Extended)**
**PIC16C711-20 (Commercial, Industrial, Extended)**
**PIC16LC710-04 (Commercial, Industrial, Extended)**
**PIC16LC711-04 (Commercial, Industrial, Extended)**

| DC CHARACTERISTICS | | | | | | | **Standard Operating Conditions (unless otherwise stated)**<br>Operating temperature 0°C ≤ TA ≤ +70°C (commercial)<br>-40°C ≤ TA ≤ +85°C (industrial)<br>-40°C ≤ TA ≤ +125°C (extended)<br>Operating voltage VDD range as described in DC spec Section 11.1 and Section 11.2. |
|---|---|---|---|---|---|---|---|
| **Param No.** | **Characteristic** | **Sym** | **Min** | **Typ †** | **Max** | **Units** | **Conditions** |
| | **Input Low Voltage** | | | | | | |
| | I/O ports | VIL | | | | | |
| D030 | with TTL buffer | | VSS | - | 0.15VDD | V | For entire VDD range |
| D030A | | | VSS | - | 0.8V | V | 4.5 ≤ VDD ≤ 5.5V |
| D031 | with Schmitt Trigger buffer | | VSS | - | 0.2VDD | V | |
| D032 | $\overline{MCLR}$, OSC1 (in RC mode) | | VSS | - | 0.2VDD | V | |
| D033 | OSC1 (in XT, HS and LP) | | VSS | - | 0.3VDD | V | Note1 |
| | **Input High Voltage** | | | | | | |
| | I/O ports | VIH | | - | | | |
| D040 | with TTL buffer | | 2.0 | - | VDD | V | 4.5 ≤ VDD ≤ 5.5V |
| D040A | | | 0.25VDD + 0.8V | - | VDD | V | For entire VDD range |
| D041 | with Schmitt Trigger buffer | | 0.8VDD | - | VDD | V | For entire VDD range |
| D042 | $\overline{MCLR}$, RB0/INT | | 0.8VDD | - | VDD | V | |
| D042A | OSC1 (XT, HS and LP) | | 0.7VDD | - | VDD | V | Note1 |
| D043 | OSC1 (in RC mode) | | 0.9VDD | - | VDD | V | |
| D070 | PORTB weak pull-up current | IPURB | 50 | 250 | 400 | µA | VDD = 5V, VPIN = VSS |
| | **Input Leakage Current** (Notes 2, 3) | | | | | | |
| D060 | I/O ports | IIL | - | - | ±1 | µA | Vss ≤ VPIN ≤ VDD, Pin at hi-impedance |
| D061 | $\overline{MCLR}$, RA4/T0CKI | | - | - | ±5 | µA | Vss ≤ VPIN ≤ VDD |
| D063 | OSC1 | | - | - | ±5 | µA | Vss ≤ VPIN ≤ VDD, XT, HS and LP osc configuration |

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C7X be driven with external clock in RC mode.

2: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.


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**TABLE 13-1: CROSS REFERENCE OF DEVICE SPECS FOR OSCILLATOR CONFIGURATIONS AND FREQUENCIES OF OPERATION (COMMERCIAL DEVICES)**

| OSC | PIC16C715-04 | PIC16C715-10 | PIC16C715-20 | PIC16LC715-04 | PIC16C715/JW |
|---|---|---|---|---|---|
| RC | VDD: 4.0V to 5.5V<br>IDD: 5 mA max. at 5.5V<br>IPD: 21 µA max. at 4V<br>Freq: 4 MHz max. | VDD: 4.5V to 5.5V<br>IDD: 2.7 mA typ. at 5.5V<br>IPD: 1.5 µA typ. at 4V<br>Freq: 4 MHz max. | VDD: 4.5V to 5.5V<br>IDD: 2.7 mA typ. at 5.5V<br>IPD: 1.5 µA typ. at 4V<br>Freq: 4 MHz max. | VDD: 2.5V to 5.5V<br>IDD: 2.0 mA typ. at 3.0V<br>IPD: 0.9 µA typ. at 3V<br>Freq: 4 MHz max. | VDD: 4.0V to 5.5V<br>IDD: 5 mA max. at 5.5V<br>IPD: 21 µA max. at 4V<br>Freq: 4 MHz max. |
| XT | VDD: 4.0V to 5.5V<br>IDD: 5 mA max. at 5.5V<br>IPD: 21 µA max. at 4V<br>Freq: 4 MHz max. | VDD: 4.5V to 5.5V<br>IDD: 2.7 mA typ. at 5.5V<br>IPD: 1.5 µA typ. at 4V<br>Freq: 4 MHz max. | VDD: 4.5V to 5.5V<br>IDD: 2.7 mA typ. at 5.5V<br>IPD: 1.5 µA typ. at 4V<br>Freq: 4 MHz max. | VDD: 2.5V to 5.5V<br>IDD: 2.0 mA typ. at 3.0V<br>IPD: 0.9 µA typ. at 3V<br>Freq: 4 MHz max. | VDD: 4.0V to 5.5V<br>IDD: 5 mA max. at 5.5V<br>IPD: 21 µA max. at 4V<br>Freq: 4 MHz max. |
| HS | VDD: 4.5V to 5.5V<br>IDD: 13.5 mA typ. at 5.5V<br>IPD: 1.5 µA typ. at 4.5V<br>Freq: 4 MHz max. | VDD: 4.5V to 5.5V<br>IDD: 30 mA max. at 5.5V<br>IPD: 1.5 µA typ. at 4.5V<br>Freq: 10 MHz max. | VDD: 4.5V to 5.5V<br>IDD: 30 mA max. at 5.5V<br>IPD: 1.5 µA typ. at 4.5V<br>Freq: 20 MHz max. | Do not use in HS mode | VDD: 4.5V to 5.5V<br>IDD: 30 mA max. at 5.5V<br>IPD: 1.5 µA typ. at 4.5V<br>Freq: 10 MHz max. |
| LP | VDD: 4.0V to 5.5V<br>IDD: 52.5 µA typ. at 32 kHz, 4.0V<br>IPD: 0.9 µA typ. at 4.0V<br>Freq: 200 kHz max. | Do not use in LP mode | Do not use in LP mode | VDD: 2.5V to 5.5V<br>IDD: 48 µA max. at 32 kHz, 3.0V<br>IPD: 5.0 µA max. at 3.0V<br>Freq: 200 kHz max. | VDD: 2.5V to 5.5V<br>IDD: 48 µA max. at 32 kHz, 3.0V<br>IPD: 5.0 µA max. at 3.0V<br>Freq: 200 kHz max. |

The shaded sections indicate oscillator selections which are tested for functionality, but not for MIN/MAX specifications. It is recommended that the user select the device type that ensures the specifications required.

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## 13.5 Timing Diagrams and Specifications

**FIGURE 13-2: EXTERNAL CLOCK TIMING**

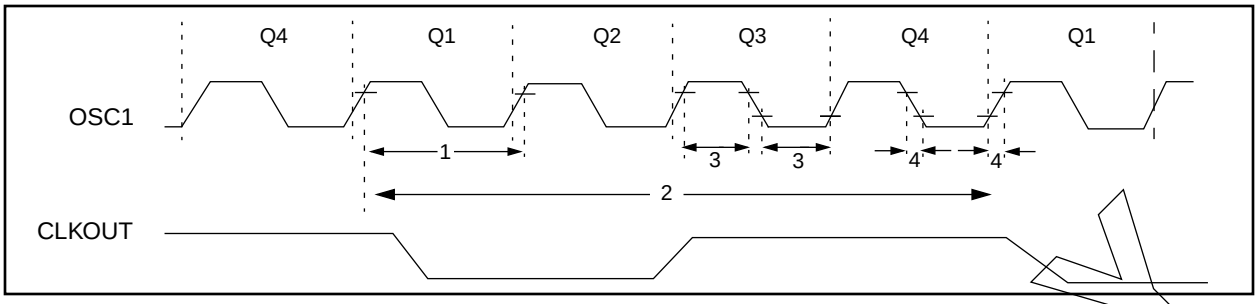


**TABLE 13-2: CLOCK TIMING REQUIREMENTS**

| Parameter No. | Sym | Characteristic | Min | Typ† | Max | Units | Conditions |
|---|---|---|---|---|---|---|---|
| | Fos | **External CLKIN Frequency (Note 1)** | DC | — | 4 | MHz | XT osc mode |
| | | | DC | — | 4 | MHz | HS osc mode (PIC16C715-04) |
| | | | DC | — | 20 | MHz | HS osc mode (PIC16C715-20) |
| | | | DC | — | 200 | kHz | LP osc mode |
| | | **Oscillator Frequency (Note 1)** | DC | — | 4 | MHz | RC osc mode |
| | | | 0.1 | — | 4 | MHz | XT osc mode |
| | | | 4 | — | 4 | MHz | HS osc mode (PIC16C715-04) |
| | | | 4 | — | 10 | MHz | HS osc mode (PIC16C715-10) |
| | | | 4 | — | 20 | MHz | HS osc mode (PIC16C715-20) |
| | | | 5 | — | 200 | kHz | LP osc mode |
| 1 | Tosc | **External CLKIN Period (Note 1)** | 250 | — | — | ns | XT osc mode |
| | | | 250 | — | — | ns | HS osc mode (PIC16C715-04) |
| | | | 100 | — | — | ns | HS osc mode (PIC16C715-10) |
| | | | 50 | — | — | ns | HS osc mode (PIC16C715-20) |
| | | | 5 | — | — | µs | LP osc mode |
| | | **Oscillator Period (Note 1)** | 250 | — | — | ns | RC osc mode |
| | | | 250 | — | 10,000 | ns | XT osc mode |
| | | | 250 | — | 250 | ns | HS osc mode (PIC16C715-04) |
| | | | 100 | — | 250 | ns | HS osc mode (PIC16C715-10) |
| | | | 50 | — | 250 | ns | HS osc mode (PIC16C715-20) |
| | | | 5 | — | — | µs | LP osc mode |
| 2 | TCY | **Instruction Cycle Time (Note 1)** | 200 | — | DC | ns | TCY = 4/FOSC |
| 3 | TosL, TosH | **External Clock in (OSC1) High or Low Time** | 50 | — | — | ns | XT oscillator |
| | | | 2.5 | — | — | µs | LP oscillator |
| | | | 10 | — | — | ns | HS oscillator |
| 4 | TosR, TosF | **External Clock in (OSC1) Rise or Fall Time** | — | — | 25 | ns | XT oscillator |
| | | | — | — | 50 | ns | LP oscillator |
| | | | — | — | 15 | ns | HS oscillator |

† Data in "Typ" column is at 5V, 25˚C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (TCY) equals four times the input oscillator time-base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1/CLKIN pin. When an external clock input is used, the "Max." cycle time limit is "DC" (no clock) for all devices. OSC2 is disconnected (has no loading) for the PIC16C715.

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### 15.1 DC Characteristics: PIC16C71-04 (Commercial, Industrial) PIC16C71-20 (Commercial, Industrial)

| DC CHARACTERISTICS | | | Standard Operating Conditions (unless otherwise stated)<br>Operating temperature 0°C ≤ TA ≤ +70°C (commercial)<br>-40°C ≤ TA ≤ +85°C (industrial) | | | | |
|---|---|---|---|---|---|---|---|
| **Param No.** | **Characteristic** | **Sym** | **Min** | **Typ†** | **Max** | **Units** | **Conditions** |
| D001<br>D001A | Supply Voltage | VDD | 4.0<br>4.5 | -<br>- | 6.0<br>5.5 | V<br>V | XT, RC and LP osc configuration<br>HS osc configuration |
| D002* | RAM Data Retention Voltage (Note 1) | VDR | - | 1.5 | - | V | |
| D003 | VDD start voltage to ensure internal Power-on Reset signal | VPOR | - | VSS | - | V | See section on Power-on Reset for details |
| D004* | VDD rise rate to ensure internal Power-on Reset signal | SVDD | 0.05 | - | - | V/ms | See section on Power-on Reset for details |
| D010<br><br><br>D013 | Supply Current (Note 2) | IDD | -<br><br><br>- | 1.8<br><br><br>13.5 | 3.3<br><br><br>30 | mA<br><br><br>mA | XT, RC osc configuration<br>FOSC = 4 MHz, VDD = 5.5V (Note 4)<br><br>HS osc configuration<br>FOSC = 20 MHz, VDD = 5.5V |
| D020<br>D021<br>D021A | Power-down Current (Note 3) | IPD | -<br>-<br>- | 7<br>1.0<br>1.0 | 28<br>14<br>16 | µA<br>µA<br>µA | VDD = 4.0V, WDT enabled, -40°C to +85°C<br>VDD = 4.0V, WDT disabled, -0°C to +70°C<br>VDD = 4.0V, WDT disabled, -40°C to +85°C |

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail to rail; all I/O pins tristated, pulled to VDD
$\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and VSS.

4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula Ir = VDD/2Rext (mA) with Rext in kOhm.


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|---|---|---|---|---|

### 15.4 Timing Parameter Symbology

The timing parameter symbols have been created following one of the following formats:

1. TppS2ppS
2. TppS

| T | | | |
|---|---|---|---|
| F | Frequency | T | Time |

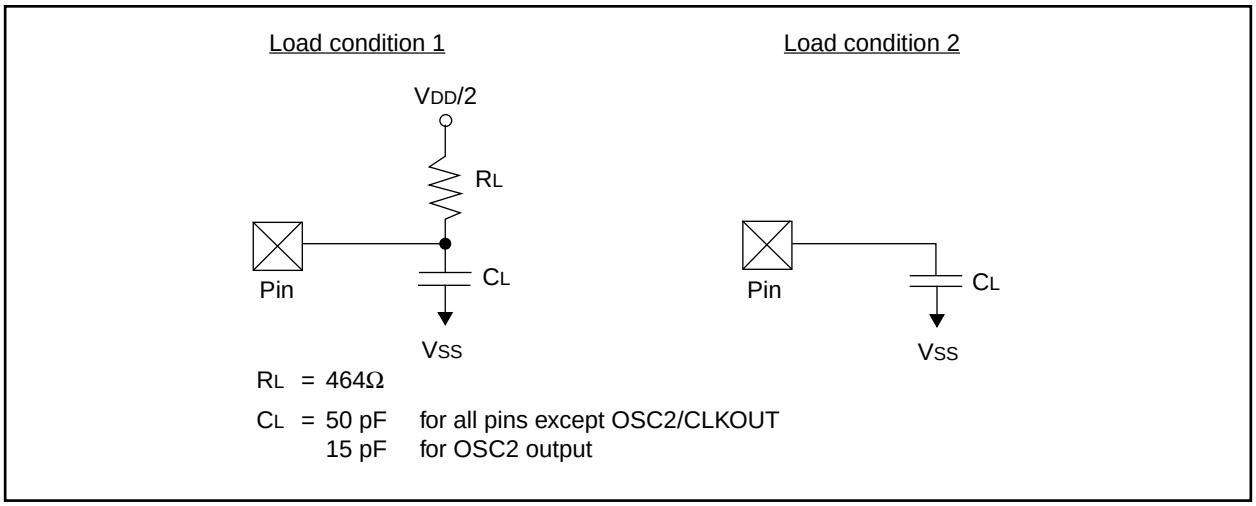
Lowercase letters (pp) and their meanings:

| pp | | | |
|---|---|---|---|
| cc | CCP1 | osc | OSC1 |
| ck | CLKOUT | rd | $\overline{RD}$ |
| cs | $\overline{CS}$ | rw | $\overline{RD}$ or $\overline{WR}$ |
| di | SDI | sc | SCK |
| do | SDO | ss | $\overline{SS}$ |
| dt | Data in | t0 | T0CKI |
| io | I/O port | t1 | T1CKI |
| mc | $\overline{MCLR}$ | wr | $\overline{WR}$ |

Uppercase letters and their meanings:

| S | | | |
|---|---|---|---|
| F | Fall | P | Period |
| H | High | R | Rise |
| I | Invalid (Hi-impedance) | V | Valid |
| L | Low | Z | Hi-impedance |

**FIGURE 15-1: LOAD CONDITIONS**





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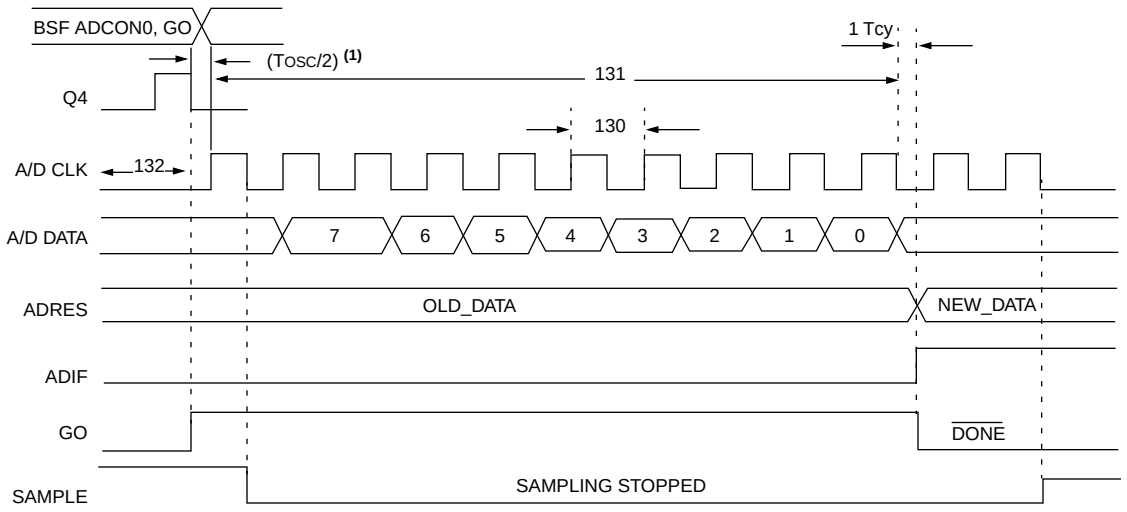
|---|---|---|---|---|

**FIGURE 15-6: A/D CONVERSION TIMING**




Note 1: If the A/D clock source is selected as RC, a time of TCY is added before the A/D clock starts. This allows the SLEEP instruction to be executed.

**TABLE 15-7: A/D CONVERSION REQUIREMENTS**

| Param No. | Sym | Characteristic | | Min | Typ† | Max | Units | Conditions |
|---|---|---|---|---|---|---|---|---|
| 130 | TAD | A/D clock period | PIC16**C**71 | 2.0 | — | — | µs | TOSC based, VREF ≥ 3.0V |
| | | | PIC16**LC**71 | 2.0 | — | — | µs | TOSC based, VREF full range |
| | | | PIC16**C**71 | 2.0 | 4.0 | 6.0 | µs | A/D RC Mode |
| | | | PIC16**LC**71 | 3.0 | 6.0 | 9.0 | µs | A/D RC Mode |
| 131 | TCNV | Conversion time (not including S/H time) (Note 1) | | — | 9.5 | — | TAD | |
| 132 | TACQ | Acquisition time | | Note 2 | 20 | — | µs | |
| | | | | 5* | — | — | µs | The minimum time is the amplifier settling time. This may be used if the "new" input voltage has not changed by more than 1 LSb (i.e., 19.5 mV @ 5.12V) from the last sampled voltage (as stated on CHOLD). |
| 134 | TGO | Q4 to A/D clock start | | — | Tosc/2§ | — | — | If the A/D clock source is selected as RC, a time of TCY is added before the A/D clock starts. This allows the SLEEP instruction to be executed. |
| 135 | TSWC | Switching from convert → sample time | | 1.5§ | — | — | TAD | |

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

§ These specifications ensured by design.

Note 1: ADRES register may be read on the following TCY cycle.

2: See Section 7.1 for min conditions.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|---|---|---|---|---|

**FIGURE 16-7: MAXIMUM IPD VS. VDD WATCHDOG DISABLED**

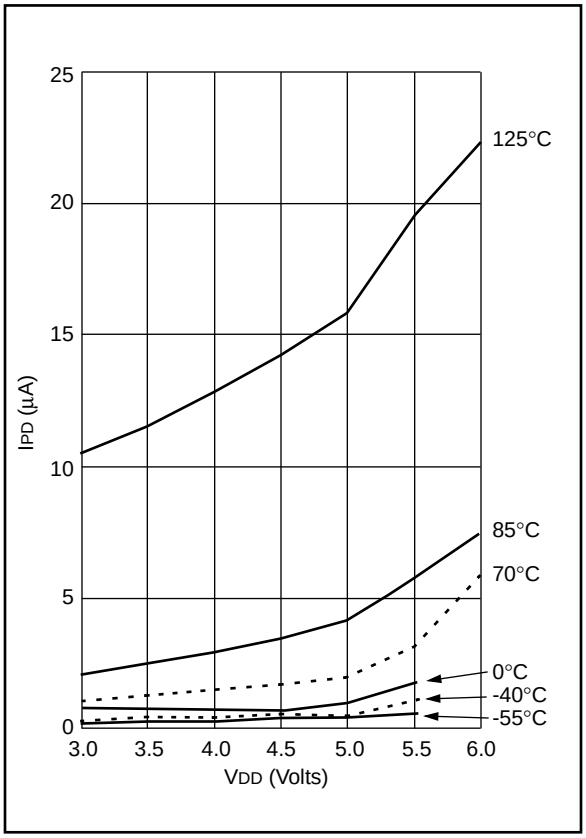
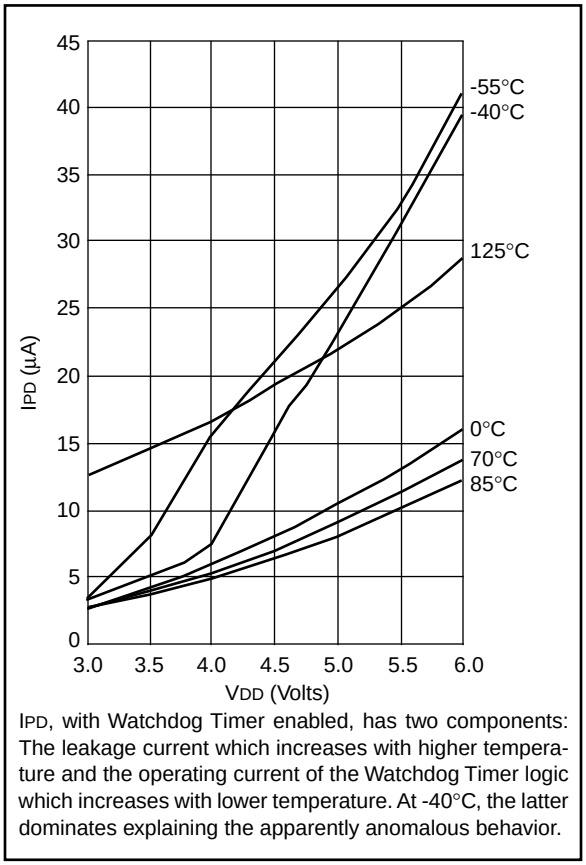
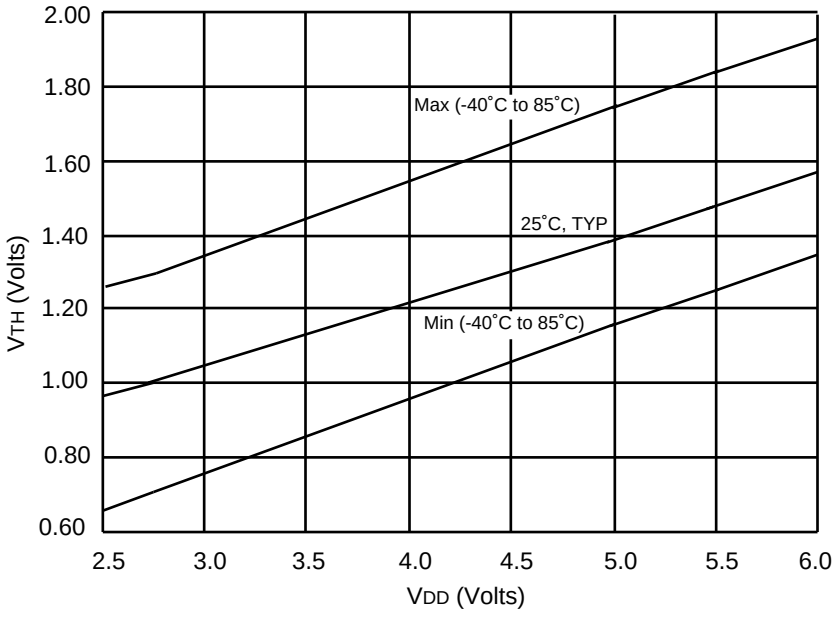



**FIGURE 16-8: MAXIMUM IPD VS. VDD WATCHDOG ENABLED**




IPD, with Watchdog Timer enabled, has two components: The leakage current which increases with higher temperature and the operating current of the Watchdog Timer logic which increases with lower temperature. At -40°C, the latter dominates explaining the apparently anomalous behavior.

**FIGURE 16-9: VTH (INPUT THRESHOLD VOLTAGE) OF I/O PINS VS. VDD**




Data based on matrix samples. See first page of this section for details.

**NOTES:**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**NOTES:**